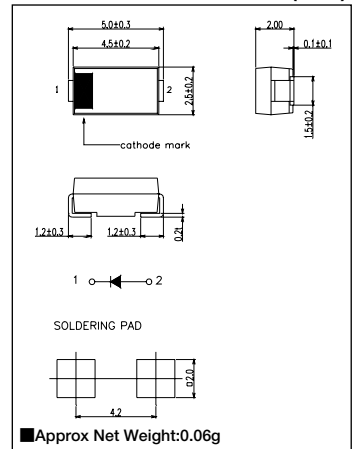


1A Avg. 200 Volts Standard Recovery Diode EC10DS2

最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	200	V
非くり返しピーク逆電圧 Non-repetitive Peak Reverse Voltage	V_{RSM}	400	V
平均整流電流 Average Rectified Forward Current	I_O	50Hz、正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load ($T_a=25^\circ\text{C}$)	0.74^{*1}
			1.0^{*2}
実効順電流 R.M.S. Forward Current	$I_F(\text{RMS})$	1.57	A
サージ順電流 Surge Forward Current	I_{FSM}	25 50Hz正弦半波、1サイクル、非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	$^\circ\text{C}$
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	$^\circ\text{C}$

OUTLINE DRAWING(mm)



電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit	
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^\circ\text{C}$, $V_{RM}=V_{RRM}$	—	—	10	μA	
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^\circ\text{C}$, $I_{FM}=1\text{A}$	—	—	1.1	V	
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	*1	—	—	157	$^\circ\text{C/W}$
			*2	—	—	108	$^\circ\text{C/W}$

*1: プリント基板実装 / Glass Epoxy Substrate mounted (Soldering Land=2×2mm, Both Sides)
 *2: アルミナ基板実装 / Alumina Substrate mounted (Soldering Lands= 2 × 2 mm, Both Sides)

定格・特性曲線

FIG.1

順電圧特性
FORWARD CURRENT VS. VOLTAGE

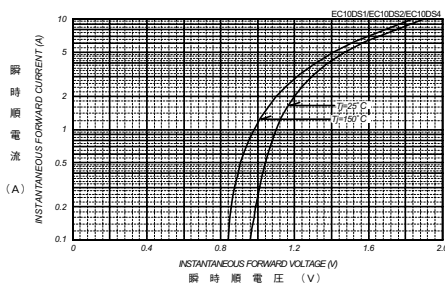


FIG.2

平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

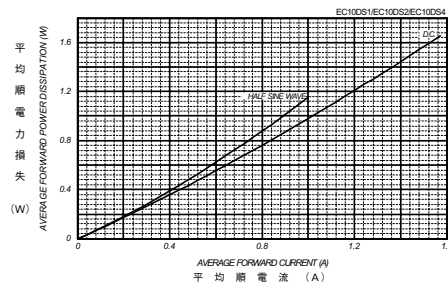


FIG.3

平均順電流 - 周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE
Glass-Epoxy Substrate Mounted (Soldering Land=2/2mm)

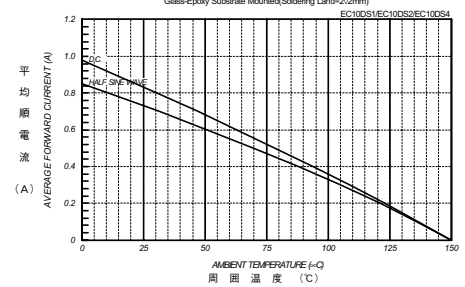


FIG.4

平均順電流 - 周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE
Alumina Substrate Mounted (Soldering Land=2/2mm)

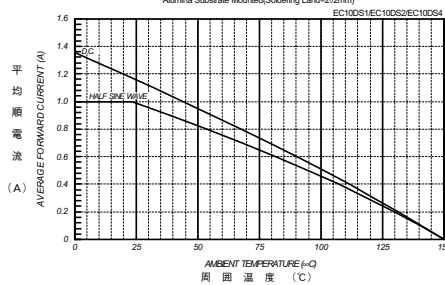


FIG.5

サージ順電流定格
SURGE CURRENT RATINGS
f=50Hz Half Sine Wave, Non-Repetitive, No Load

